

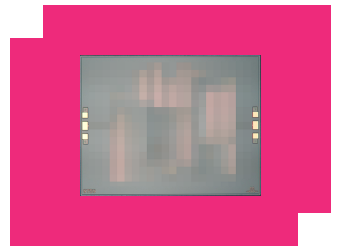
MFBP-00054CH

Passive GaAs MMIC 11.06 - 16.96 GHz Bandpass Filter

DEVICE OVERVIEW

General Description

The MFBP-00054CH passive MMIC bandpass filter die is an ideal solution for small form factor, high rejection filtering. Passive GaAs MMIC technology allows production of smaller filter constructions that replace larger form factor circuit board constructions. Tight fabrication tolerances allow for less unit to unit variation than traditional filter technologies. The MFBP-00054CH is available as a wire bondable chip. Low unit to unit variation allows for accurate simulations using the provided S2P file taken from measured production units.



[Download s-parameters here](#)

Features

- Excellent Return Loss
- High Stop Band Suppression
- Wide Stop Band with Fast Roll-Off

Applications

N/A

Functional Block Diagram



Part Ordering Options

Part Number	Description	Package	Green Status	Product Lifecycle	Export Classification
MFBP-00054CH	Passive GaAs MMIC 11.06 - 16.96 GHz Bandpass Filter	CH	RoHS REACH	Released	EAR99

Table Of Contents

■ Device Overview

General Description
Features
Applications
Functional Block Diagram

■ Port Configuration and Functions

Port Diagram
Port Functions

■ Revision History

■ Specifications

Absolute Maximum Ratings
Package Information
Electrical Specifications
Typical Performance Plots

■ Die Mounting Recommendations

Mounting and Bounding Recommendations

■ Mechanical Data

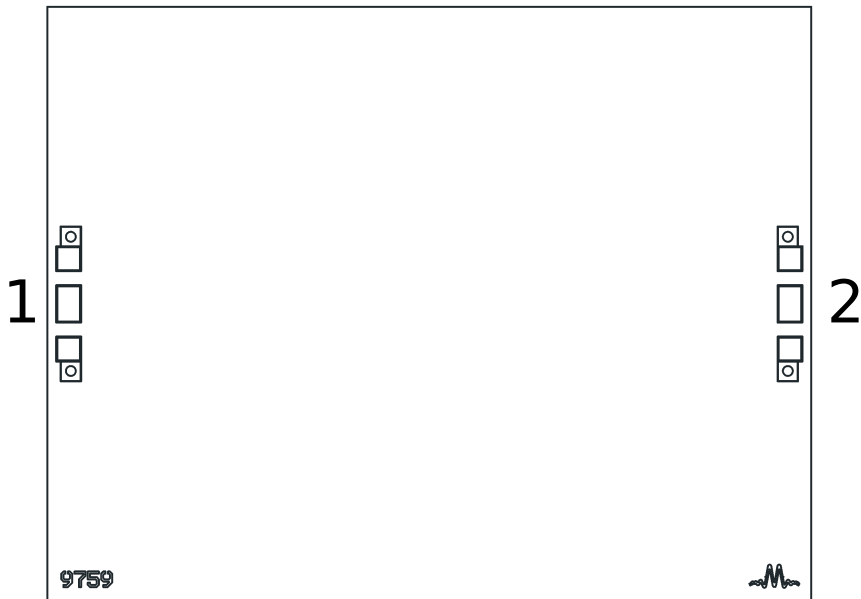
Outline Drawing

Revision History

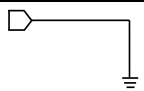
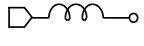
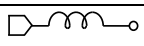
Revision Code	Revision Date	Comment
-	2024-05-22	Initial Release

Port Configuration and Functions

Port Diagram



Port Functions

Port	Function	Description	Equivalent Circuit for Package
Pad	Ground	CH package ground path is provided through the substrate and ground bond pads.	
Port 1	Input/Output	Port 1 is DC open for the CH package.	
Port 2	Input/Output	Port 2 is DC open for the CH package.	

Specifications

Absolute Maximum Ratings

The Absolute Maximum Ratings indicate limits beyond which damage may occur to the device. If these limits are exceeded, the device may be inoperable or have a reduced lifetime.

Parameter	Maximum Rating	Unit
Maximum Operating Temperature	100	°C
Maximum Storage Temperature	125	°C
Minimum Operating Temperature	-55	°C
Minimum Storage Temperature	-65	°C

Package Information

Parameter	Details	Rating
Dimensions	-	3.10 x 2.40 mm

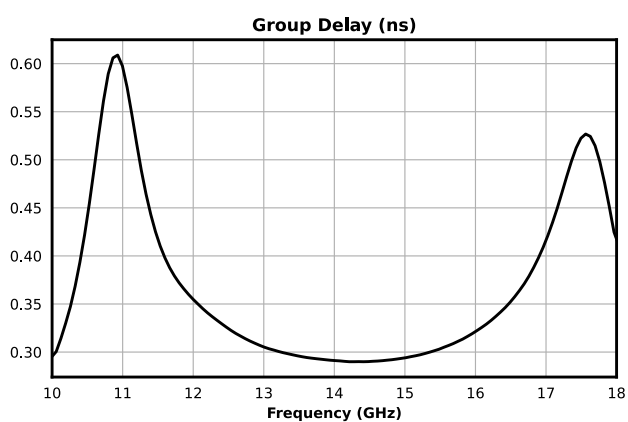
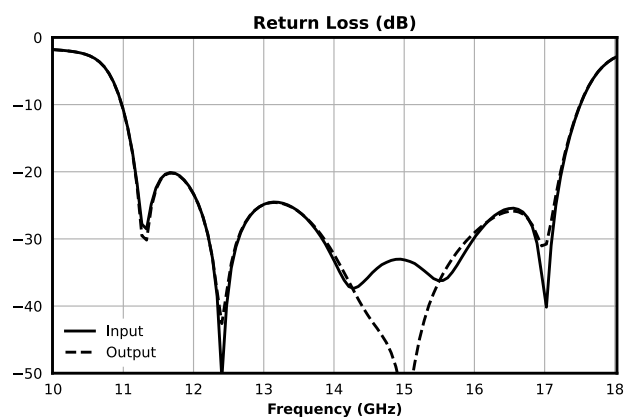
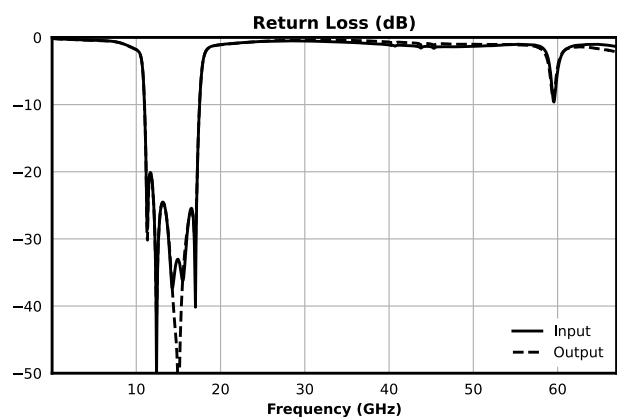
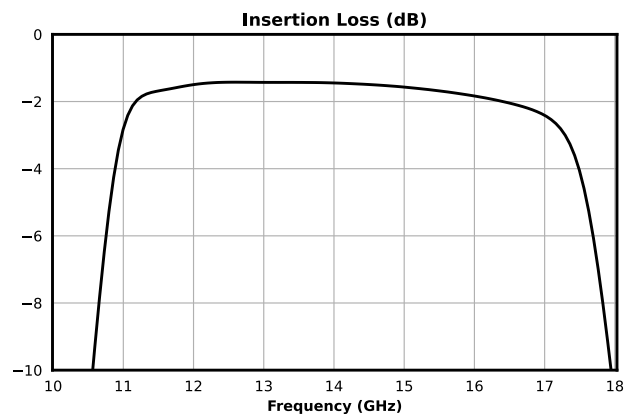
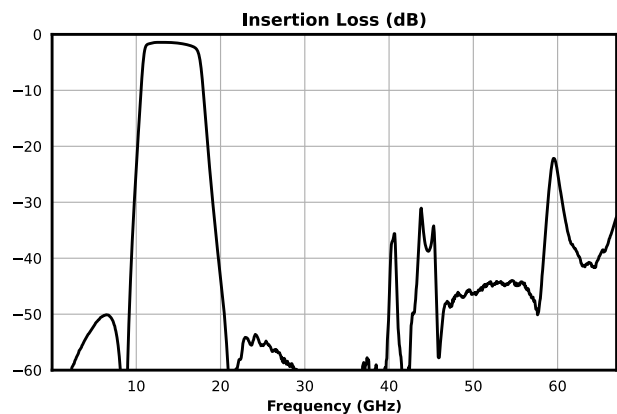
Electrical Specifications

The electrical specifications apply at TA=+25°C in a 50Ω system. Data is measured with 3 wirebonds with approximately 25 μm diameter, 50 μm height and 280 μm length. Min and Max limits are guaranteed at TA=+25°C. All bare die are 100% visually inspected and RF performance is guaranteed by sample testing.

Parameter	Test Conditions	Minimum Frequency (GHz)	Maximum Frequency (GHz)	Min	Typ	Max	Unit
Center Freq	Configuration A, 25°C	-	-	-	13.7	-	GHz
1 dBc Passband	Configuration A, 25°C	11.06	16.96	-	-	-	GHz
3 dBc Passband	Configuration A, 25°C	10.86	17.49	-	-	-	GHz
30 dBc Rejection Point	Configuration A, 25°C	9.72	19.1	-	-	-	GHz
Passband Return Loss	Configuration A, 25°C	-	-	-	28.64	-	dB
Group Delay	Configuration A, 25°C	-	-	-	312.24	-	ps
Impedance	Configuration A, 25°C	-	-	-	50	-	Ω
Insertion Loss @ fc	Configuration A, 25°C	-	-	-	1.43	-	dB

Typical Performance Plots

Data is measured with 3 wirebonds with approximately 25 μm diameter, 50 μm height and 280 μm length.



Die Mounting Recommendations

Mounting and Bonding Recommendations

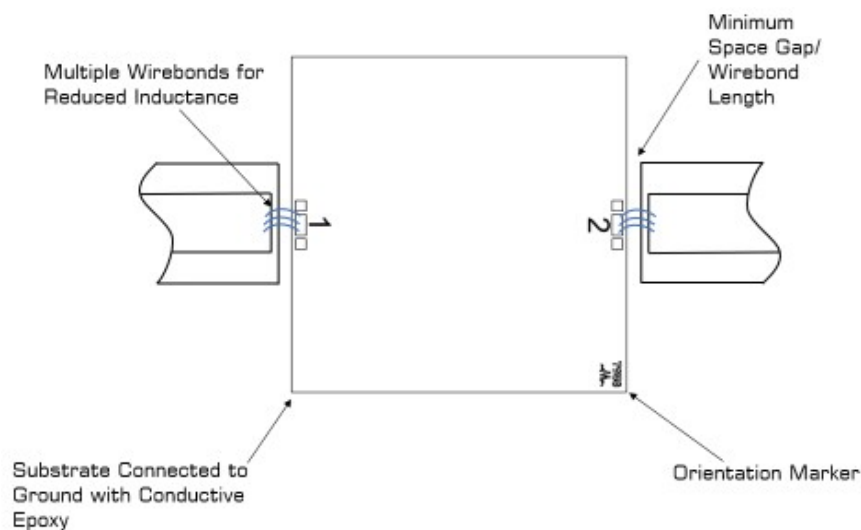
Marki MMICs should be attached directly to a ground plane with conductive epoxy. The ground plane electrical impedance should be as low as practically possible. This will prevent resonances and permit the best possible electrical performance. Datasheet performance is only guaranteed in an environment with a low electrical impedance ground.

Mounting - To epoxy the chip, apply a minimum amount of conductive epoxy to the mounting surface so that a thin epoxy fillet is observed around the perimeter of the chip. Cure epoxy according to manufacturer instructions.

Wire Bonding - Ball or wedge bond with 0.025 mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 °C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. Recommended bondwire configuration for datasheet performance is 3 wirebonds with approximately 25 µm diameter, 50 µm height and 280 µm length

Circuit Considerations– 50 Ω transmission lines should be used for all high frequency connections in and out of the chip. Wirebonds should be kept as short as possible, with multiple wirebonds recommended for higher frequency connections to reduce parasitic inductance. In circumstances where the chip more than .001" thinner than the substrate, a heat spreading spacer tab is optional to further reduce bondwire length and parasitic inductance.

Bonding Diagram



MFBP-00054CH

**Passive GaAs MMIC 11.06 - 16.96 GHz
Bandpass Filter**

Handling Precautions

General Handling

Chips should be handled with care using tweezers or a vacuum collet. Users should take precautions to protect chips from direct human contact that can deposit contaminants, like perspiration and skin oils on any of the chip's surfaces.

Static Sensitivity

GaAs MMIC devices are sensitive to ESD and should be handled, assembled, tested, and transported only in static protected environments.

Cleaning and Storage: Do not attempt to clean the chip with a liquid cleaning system or expose the bare chips to liquid. Once the ESD sensitive bags the chips are stored in are opened, chips should be stored in a dry nitrogen atmosphere.

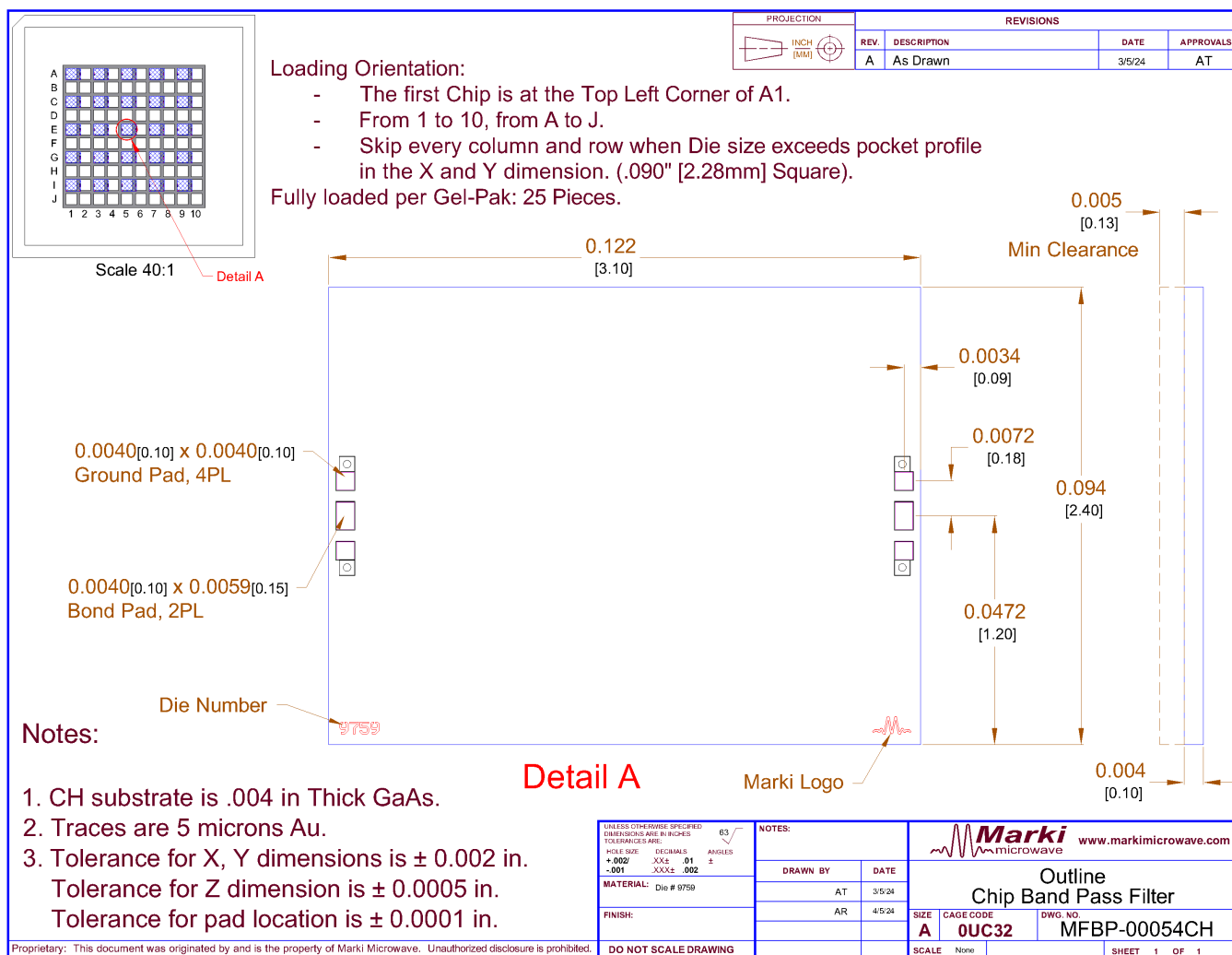
MFBP-00054CH

Passive GaAs MMIC 11.06 - 16.96 GHz
Bandpass Filter

Mechanical Data

Outline Drawing

Download : [Outline 2D Drawing](#)



MFBP-00054CH

Passive GaAs MMIC 11.06 - 16.96 GHz Bandpass Filter

DISCLAIMER

MARKI MICROWAVE, INC., ("MARKI") PROVIDES TECHNICAL SPECIFICATIONS AND DATA (INCLUDING DATASHEETS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, AND OTHER INFORMATION AND RESOURCES "AS IS" AND WITH ALL FAULTS. MARKI DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT.

These resources are intended for developers skilled in the art designing with Marki products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards and other requirements. Marki makes no guarantee regarding the suitability of its products for any particular purpose, nor does Marki assume any liability whatsoever arising out of your use or application of any Marki product. Marki grants you permission to use these resources only for development of an application that uses Marki products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Marki intellectual property or to any third-party intellectual property. Marki reserves the right to make changes to the product(s) or information contained herein without notice.

MARKI MICROWAVE and T3 MIXER are trademarks or registered trademarks of Marki Microwave, Inc. All other trademarks used are the property of their respective owners.

© 2024, Marki Microwave, Inc